

ABSTRACT OF THE DISCLOSURE

[0021] Substrate reinforcement in a land grid array (LGA) package is provided. One embodiment is an LGA package for clamping to an interposer socket on a printed circuit board. One such LGA package comprises a substrate, a die attached to the upper surface of the substrate, a lid attached to the upper surface of the die, and a substrate reinforcement member attached to the upper surface of the substrate and separated from the lid.